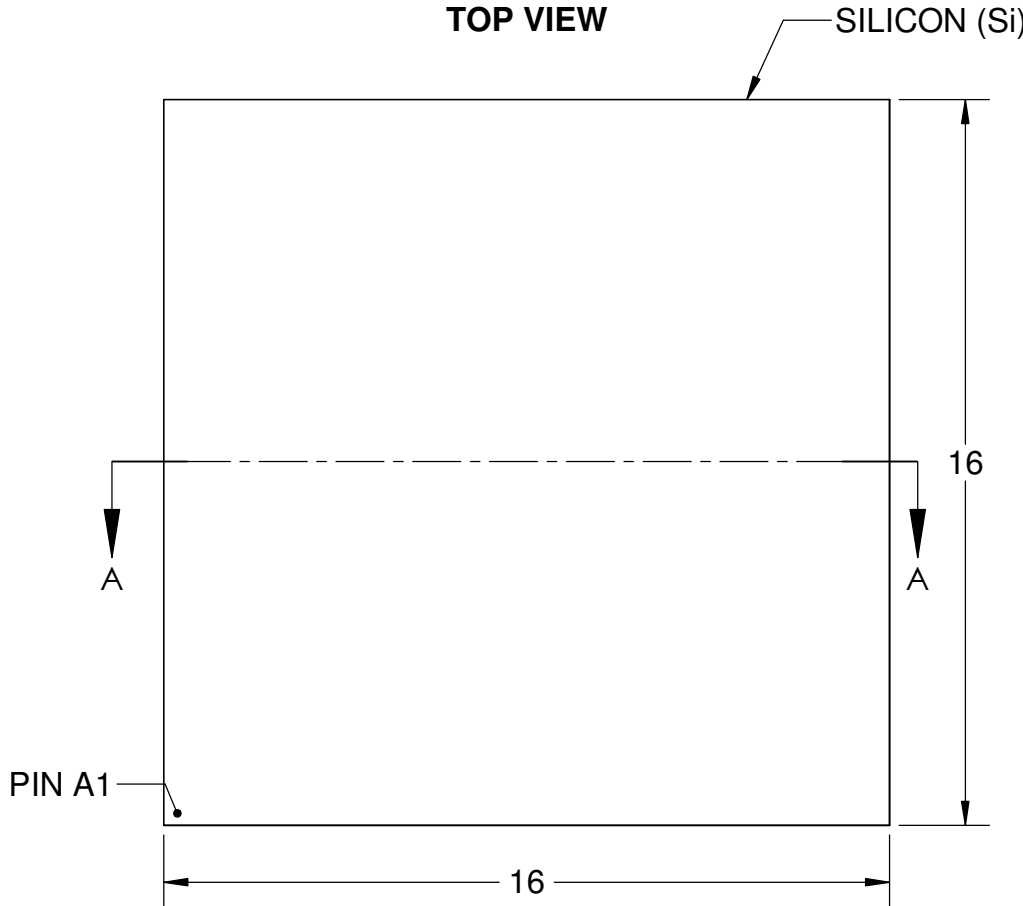
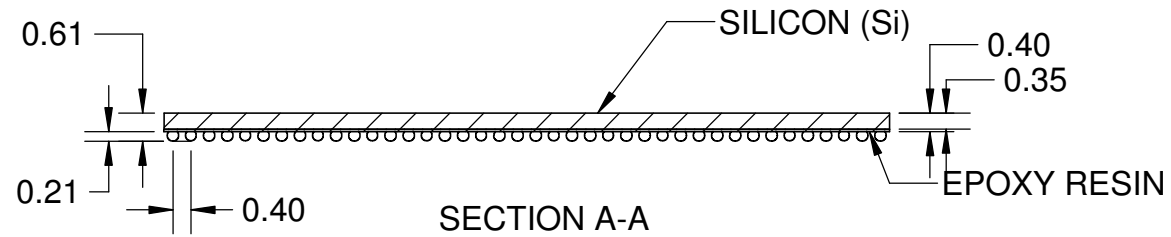
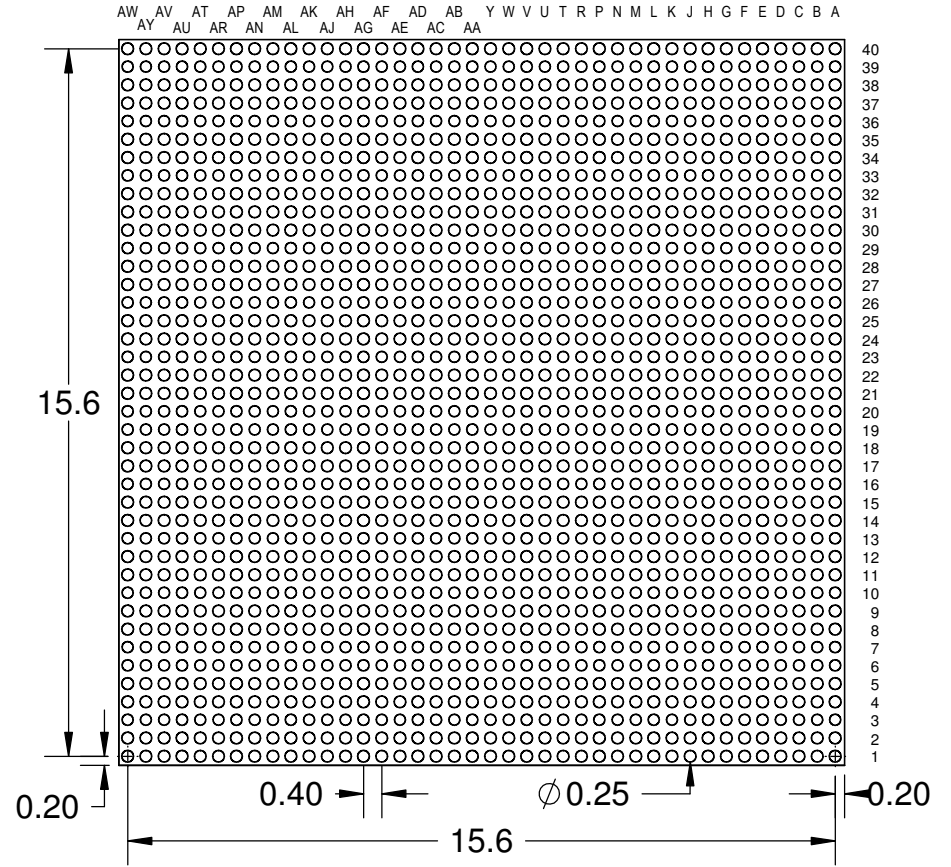


TOP VIEW



SILICON (Si)

BALL VIEW



SECTION A-A

Notes: (Unless Otherwise Specified).

- 1) ALL DIMENSIONS ARE IN MM.
- 2) SOLDER BALL ALLOY:
STANDARD: SAC305 (Sn96.5/Ag3.0/Cu0.5).
- 3) BALL DIAMETER (BEFORE REFLOW): 0.25mm.
- 4) NON-SOLDER MASK DEFINED PAD.
- 5) PAD Cu DIAMETER: 0.20mm.
- 6) SUBSTRATE MATERIAL: Si (SILICON).
- 7) DAISY CHAIN PATTERN (SEE PAGE 2).

PART NUMBER TABLE				
PART NUMBER	BALL ALLOY	Pb-FREE	RoHS	Si DIE
WLP1600T.4C-DC407D	Sn96.5/Ag3.0/Cu0.5	YES	YES	YES

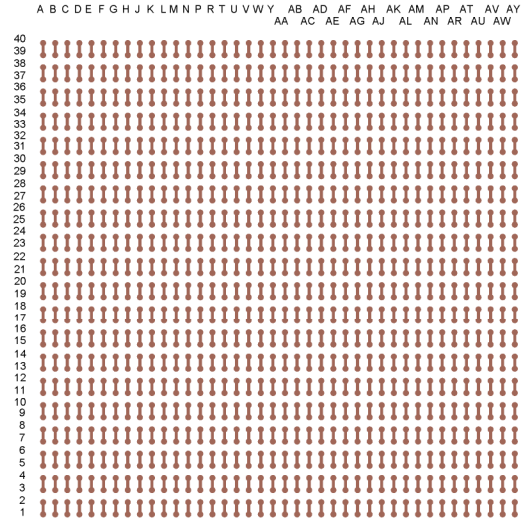
APPROVALS	DATE	TopLine®			
DRAWN T. Au	01/18/18				
ENG M. Hart	01/18/18	TITLE WLP1600T.4C-DC407D 1600 BALL P-0.4mm (TEG0408)			
MFG		SCALE	SIZE A	DRAWING NO. 544070	REV A
QA					
CUST					
REVISED		DO NOT SCALE DRAWING			SHEET 1 OF 2

DAISY CHAIN PATTERN

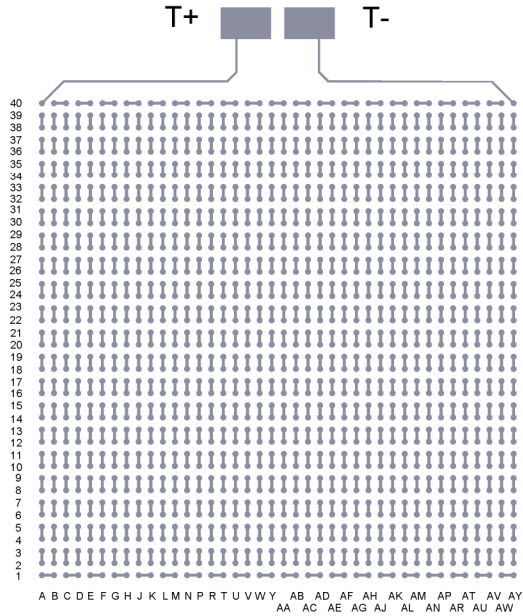
BALL VIEW



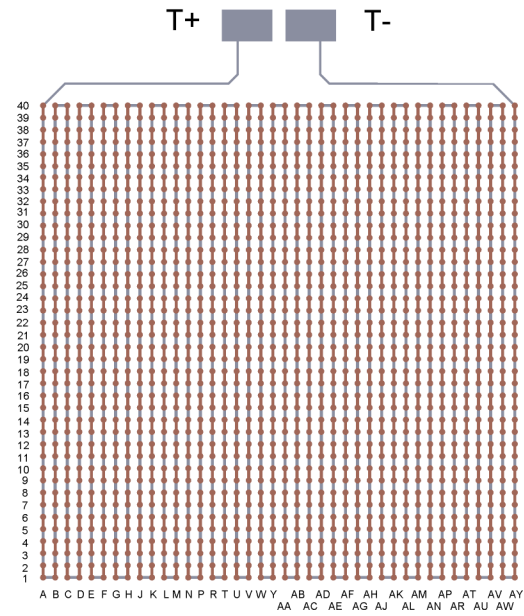
BOTTOM SIDE
(TOP X-RAY VIEW)



TOP VIEW



AFTER MOUNTING
TO TEST BOARD
(TOP X-RAY VIEW)



Notes:

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER 0.20mm (7.9mil).
- 3) PCB DAISY CHAIN TRACING LINE WIDTH 0.10mm (3.9mil).

TopLine®			
TITLE		WLP1600T.4C-DC407D 1600 BALL P-0.4mm (TEG0408)	
SCALE	SIZE	DRAWING NO.	REV
	A	544070	A
DO NOT SCALE DRAWING			SHEET 2 OF 2